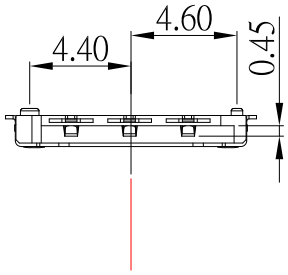
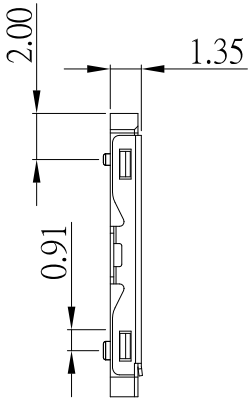
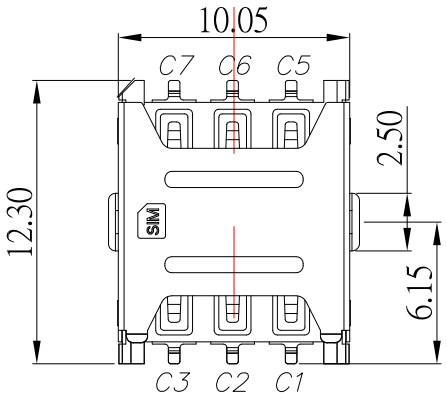
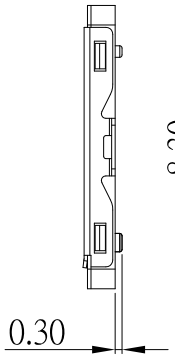
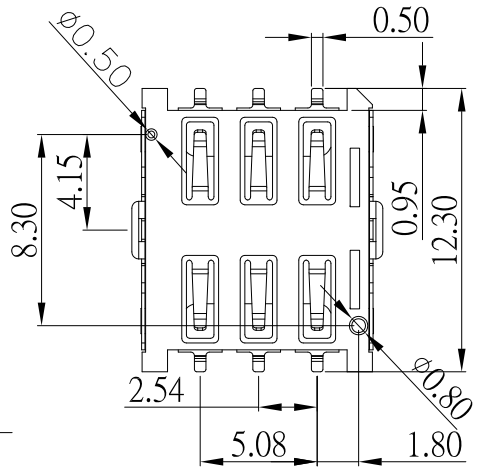
SIM pin assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

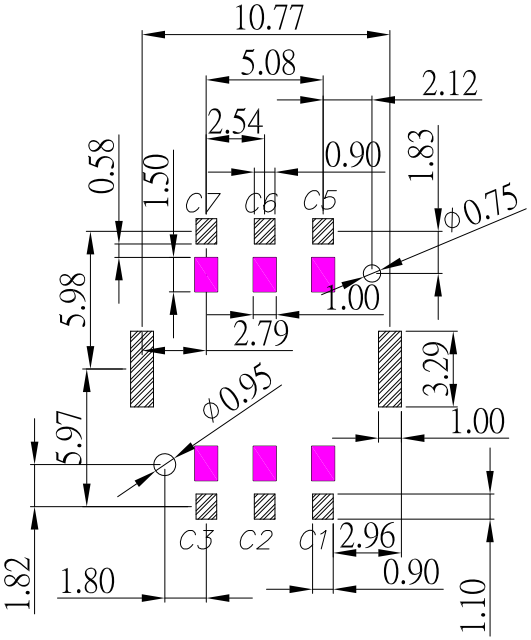








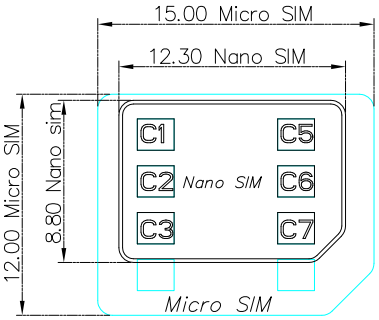


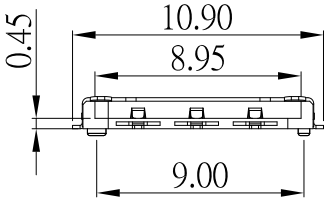


PCB逼空位置

RECOMMENDED PCB LAYOUT

P.C.B LAYOUT MOUNTING PATTERN





MATERIALS:

1. HOUSING : HIGH TEMPERATURE THERMOPLASTIC
2. CONTACT : PHOSPHOR BRONZE
3. SHELL : SUS

Finish:

1. Finish: CONTACT: PLATED GOLD IN MATING AREA ;
   GOLD PLATED ON SOLDER BALLS ;
   NICKEL UNDER PLATED OVERALL
2. SHELL: NICKEL UNDER PLATED SURFACE LAYER

SPECIFICATION:

1. CURRENT RATING : 0.5 mA AC / DC MAX.
2. VOLTAGE RATING : 125V AC / DC
3. INSULATION RESISTANCE : 1000MΩ MIN.
4. CONTACT RESISTANCE : 100mΩ MAX.
5. OPERATING TEMPERATURE RANGE : -40°C TO +85°C.
6. STORAGE TEMPERATURE RANGE : -40°C TO +85°C.

ITEM NO.	DESCRIPTION	DRAWN	DATE
2	修正尺寸標示	Jack	020123
1	更新OPERATING TEMPERATURE RANGE	Jack	101221

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED : Up to 5 ±0.2; Above 5 ~ 15 ±0.3; Above 15 ~ 30 ±0.4; Above 30 ~ 50 ±0.5; Angle ±0.3

3RD. ANGEL'S | UNITS MM

DRAWN BY: Jack Lu	DATE 02/01/23	MAT'L	
CHECKED BY: Jacky Chen	DATE 02/01/23	FINISH	
APPROVED BY: Tony Kao	DATE 02/01/23	SCALE 1 : 1	SHEET NO. 1 of 1

TITLE	CONNECTOR		
MODLE	Nano SIM CARD NO PUSH 1.35H 有柱		
DWG NO.	NSIM-0201G06A-S267	SIZE	A4
PART NO.	NSIM-0201G06A-S267	VER	R2